

TMS320C6204 MicroStar BGA Discontinued and Redesigned



ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

Table of Contents

1 Package Redesign Details..... 2

Trademarks

MicroStar BGA™ and MicroStar Junior™ are trademarks of Texas Instruments.
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1 Package Redesign Details

Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nfBGA package. This nfBGA package offers datasheet-equivalent electrical performance. It is also footprint equivalent to the MicroStar BGA. For more details, please refer to this [nfBGA Packaging Application Report](#).

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

Table 1-1. Package Designator

Old Package Designator	New Package Designator
GHK	GWT
ZHK	ZWT

Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

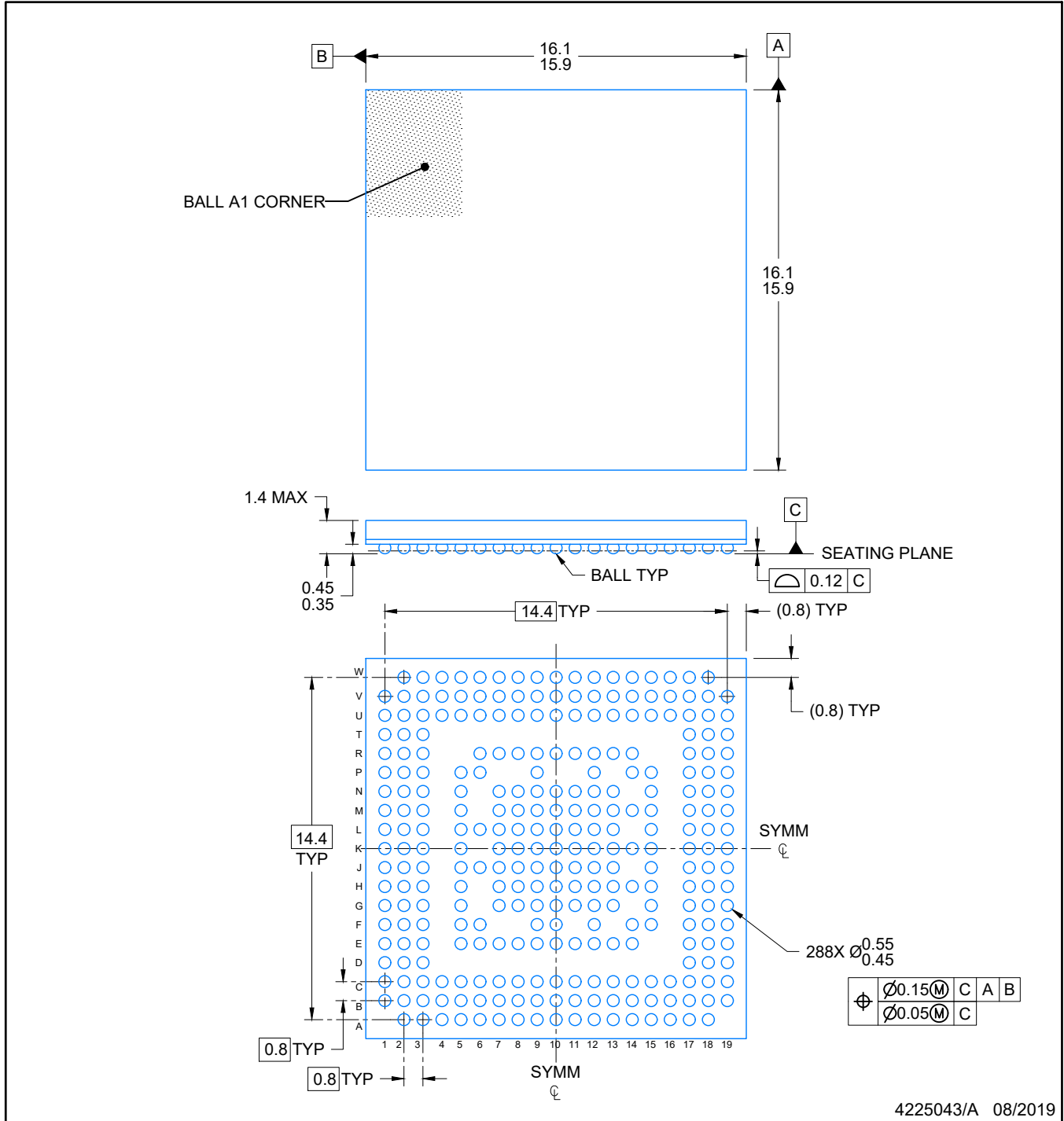
These devices have now been converted to an nfBGA package.

Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

Table 1-2. Devices and Nomenclature

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nfBGA Device	Device Datasheet
TMS320C6204	TMS320C6204GHKA200	TMS320C6204GWTA200	SPRS152
TMS320C6204	TMS320C6204ZHK200	TMS320C6204ZWT200	SPRS152
TMS320C6204	TMS320C6204ZHKA200	TMS320C6204ZWTA200	SPRS152

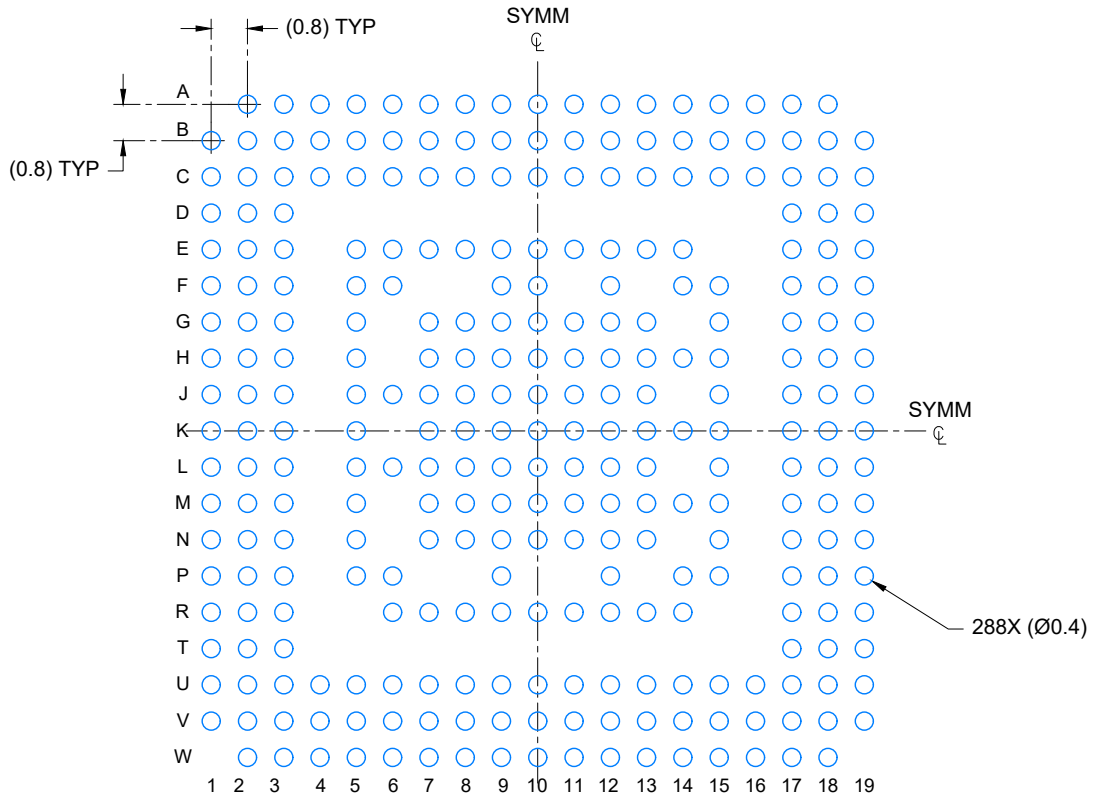


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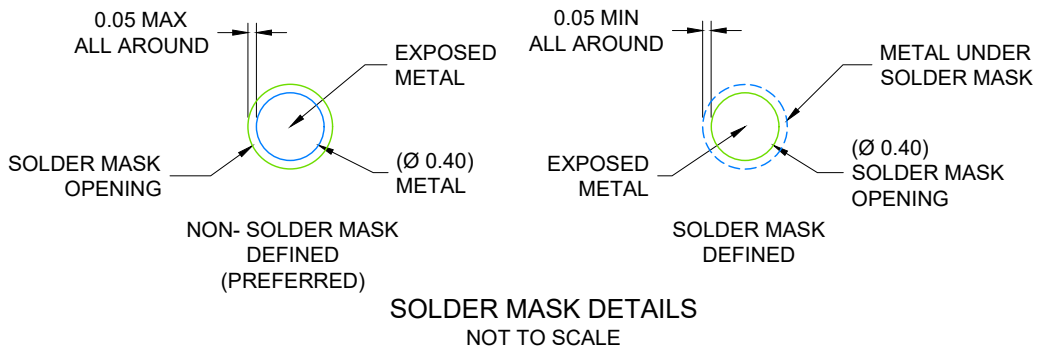
NOTES:

NanoFree is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 6X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

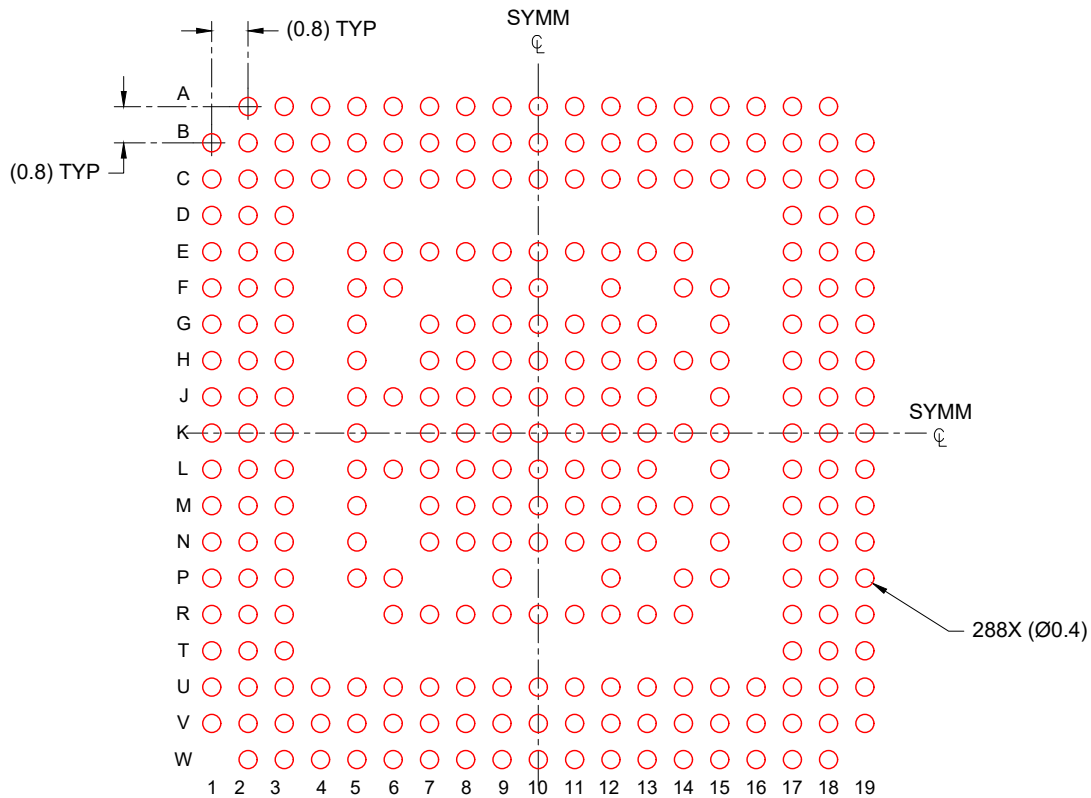
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

GWT0288A

NFBGA - 1.4 mm max height

PLASTIC BALL GRID ARRAY

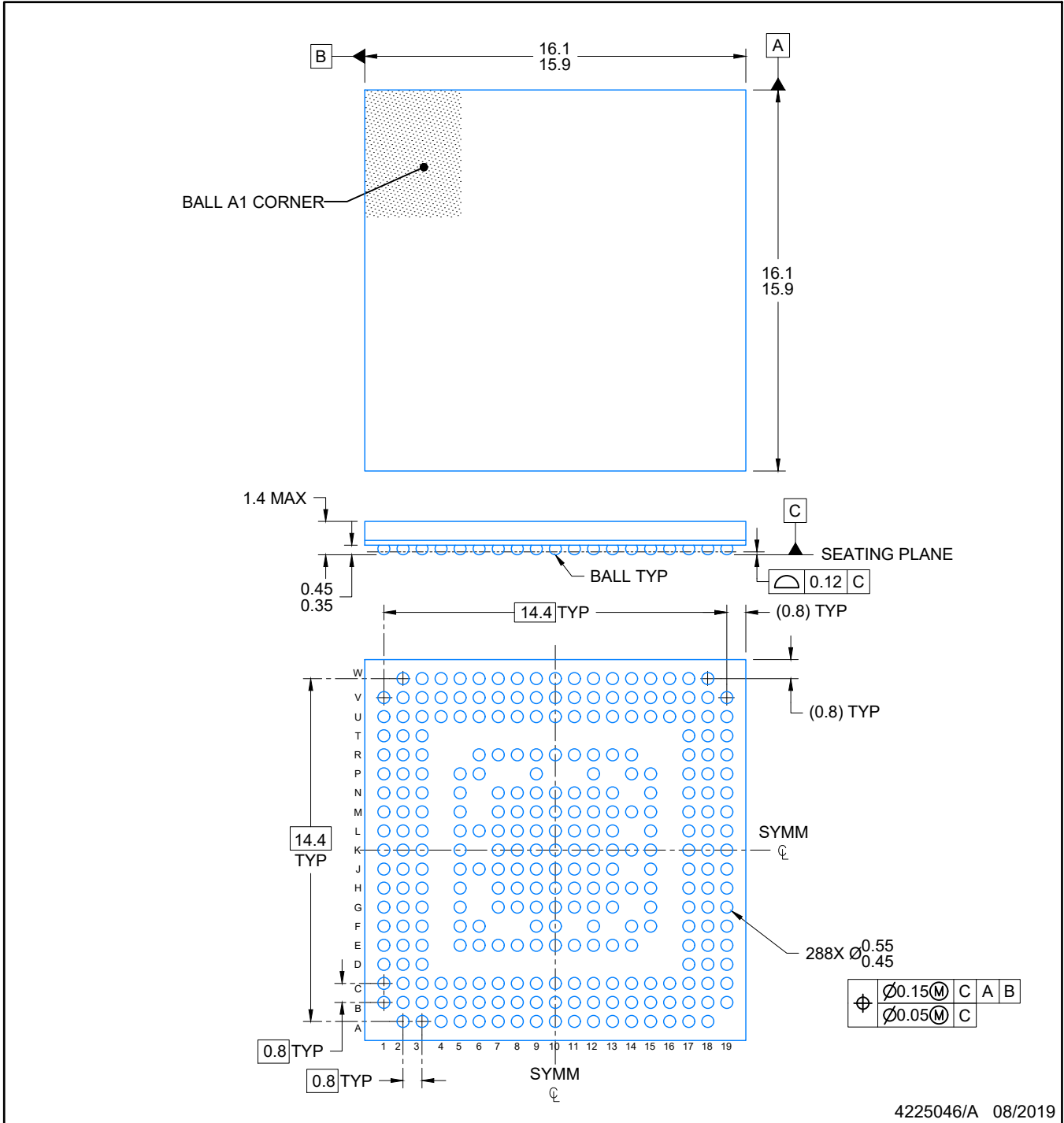


SOLDER PASTE EXAMPLE
BASED ON 0.150 mm THICK STENCIL
SCALE: 6X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

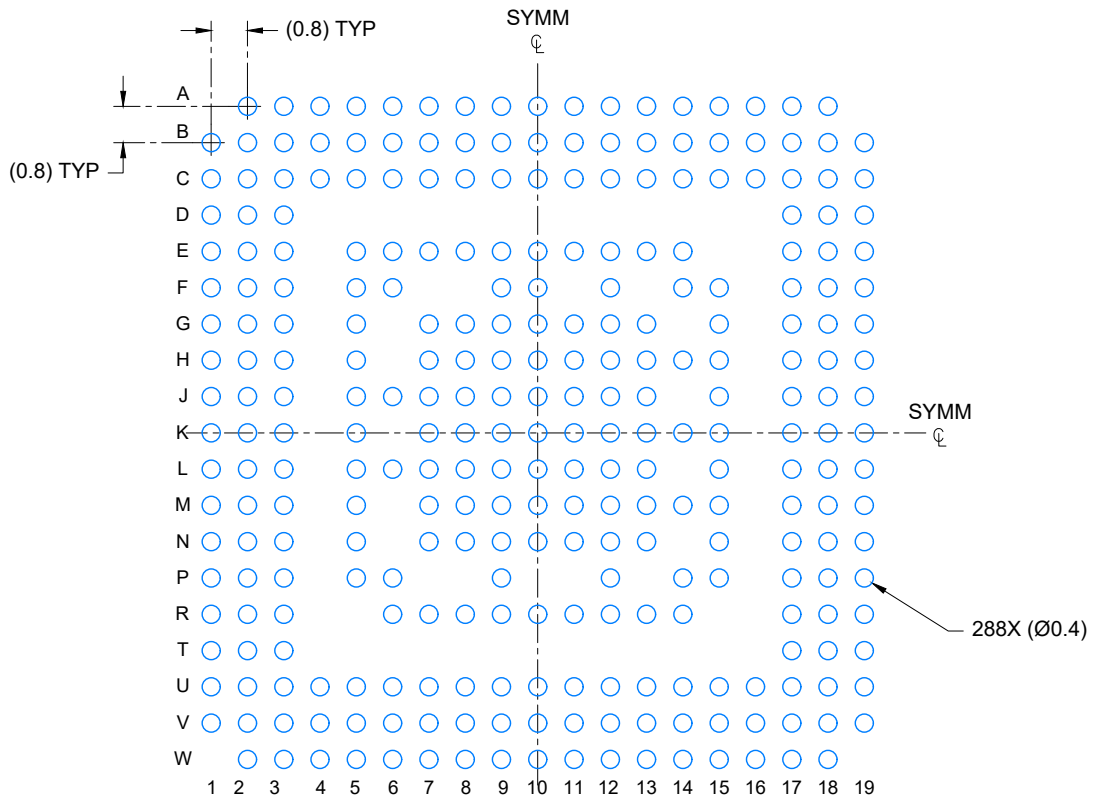


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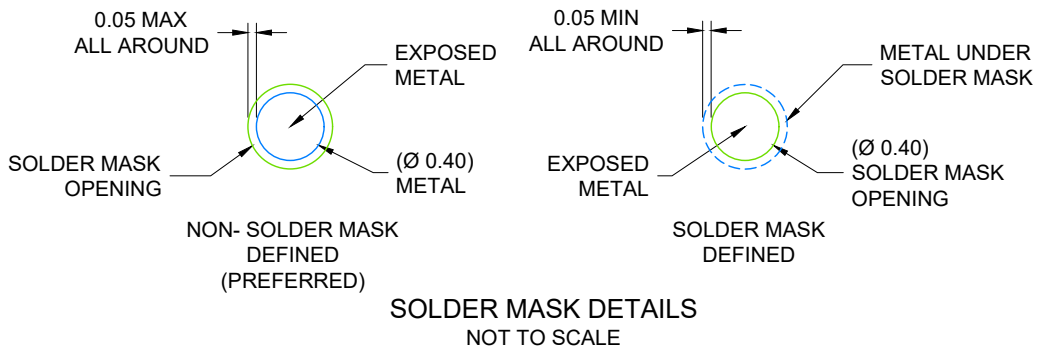
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2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 6X



SOLDER MASK DETAILS
NOT TO SCALE

4225046/A 08/2019

NOTES: (continued)

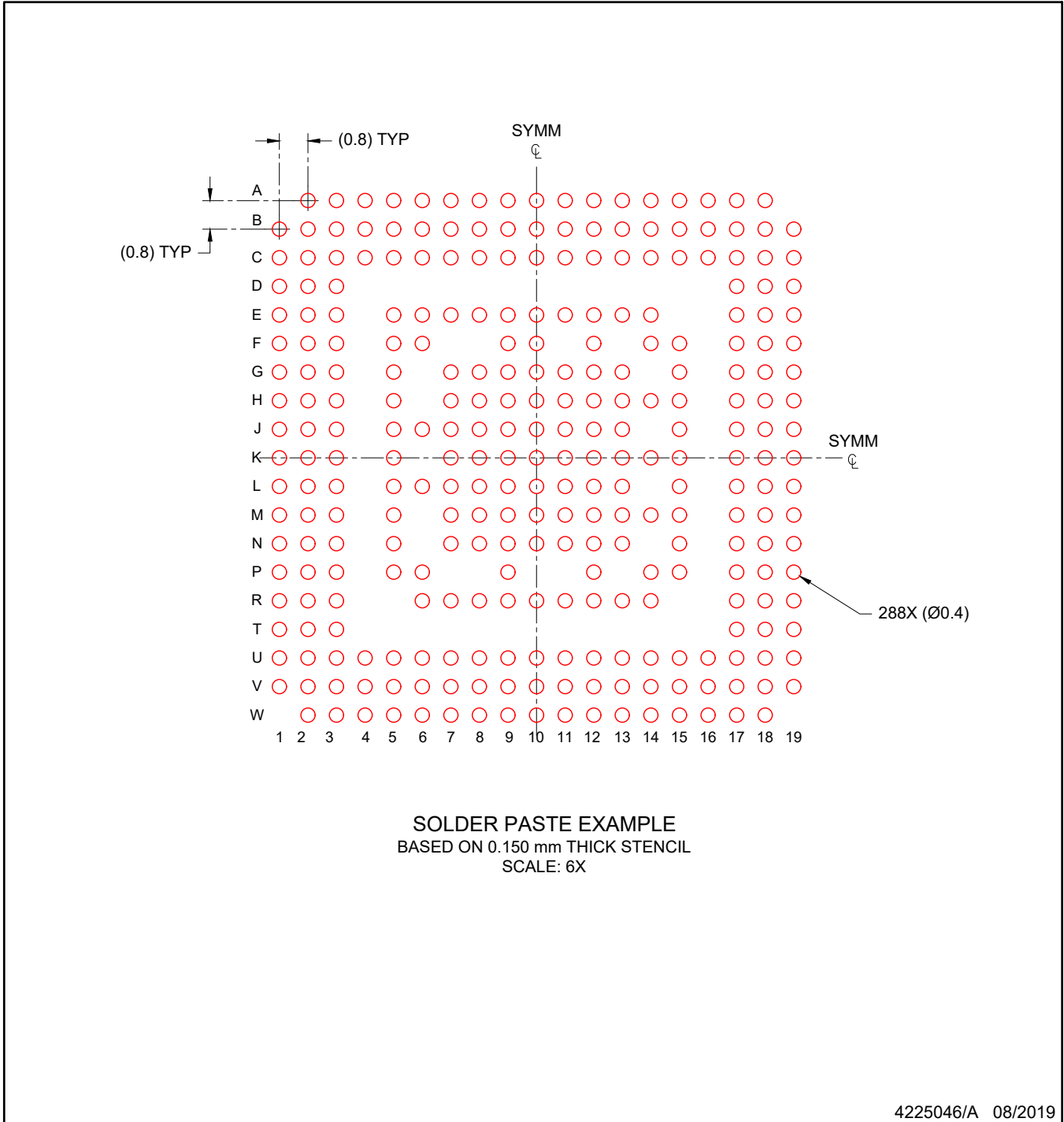
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

ZWT0288A

NFBGA - 1.4 mm max height

PLASTIC BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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